

REMARKS

Careful consideration has been given by the applicants to the Examiner's comments and rejection of the claims, as set forth in the outstanding Office Action, and favorable reconsideration and allowance of the application, as amended herein, is earnestly solicited.

Applicants note the Examiner's reiteration of the previous grounds of rejection, with regard to 35 U.S. C. §112, first paragraph, in objecting to the terminology "high-strength" in defining the laminate. However, although applicants respectfully submit that this term is quite clear in the context of the present invention in providing a structural support for a wire bonded circuit device, in order to meet the Examiner's requirements, applicants have deleted the term "high-strength" from Claim 13 and indicated that this is primarily directed to a laminate structural support for the device. This term is clearly defined in the present application and is deemed to be in conformance with the language requirements of the U.S. patent practice.

Furthermore, applicants note the Examiner's rejection of Claims 13 and 14 under 35 U.S.C. §103(a) as being unpatentable over the previously cited Japanese Publication No. JP 11-107112.

However, applicants respectfully take issue with the Examiner in that regard noting that although the Japanese publication does teach relationships between spacing and strength to impart accuracy and efficiency, the weave, as shown in the Japanese publication does not provide for optimized values analogous to that set forth and claimed by the present invention.

To the contrary, the Japanese publication is of a relatively general concept in nature and does not define the manner in which the optimization of the dimensions and spacings are effected in a manner analogous to that defined by the present invention and as set forth in the amended Claim 13, which now incorporates the limitation of Claim 14.

Contrary to the publication cited by the Examiner, in the Japanese specification there is no particular teaching as to how to optimize the structure of the laminate support in the wire bonded circuit so as to prevent the collapse or damage which can be incurred by a circuit pad arranged on a substrate. To this effect, it remained for the present applicants to provide the specific parameters, both as to size and spacing dimensions, which will enable the highly efficient and economical mode leading to the desired results in the support structure.

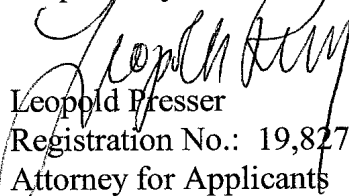
The general optimization parameters, which are set forth in the Japanese publication, do not lead to the teaching and definitions derived by the present invention, as also clearly set forth and specified in the pending claim, and applying the teachings of the Japanese publication to the present invention is deemed to be primarily a broad speculation that “possibly or potentially” the Japanese publication could lead to the intended optimization. However, this would require undue experimentation with the information provided by the Japanese publication in order to derive the specific and desired results, which are set forth and claimed herein.

The sizes of the physical parameters, which are set forth in the Japanese publication, are completely different from those defined in the present claims, which also allows for a minimum amount of weight and physical displacement. To the contrary, in the Japanese publication, the weights and parameters are of a much heavier and bulkier nature, and are not adequately suited for the wire bond circuitry of the present invention.

Accordingly, inasmuch as the amended Claim 13 clearly sets forth these particular distinctions over the art, and which are deemed to lead to unique and highly desirous results, the patentable nature of the present invention, as claimed, is deemed to be clear to one of skill in this particular technology, and the Japanese publication, in essence to some extent, teaches away from the present invention by not defining nor addressing the particular physical parameters provided for by the claimed concept.

In view of the foregoing amendments and arguments, which are deemed to clearly set forth the patentable distinctions over the art as represented by the Japanese publication, applicants respectfully request the examiner's reconsideration of the rejection of the claim and allowance of the application. However, in the event that the Examiner has any queries concerning the instantly submitted Amendment, applicants' attorney respectfully requests that he be accorded the courtesy of possibly a telephone conference to discuss any matters in need of attention.

Respectfully submitted,



Leopold Presser
Registration No.: 19,827
Attorney for Applicants

Scully, Scott, Murphy & Presser, P.C.
400 Garden City Plaza – Suite 300
Garden City, New York 11530
(516) 742-4343

LP:jy